

NOTES

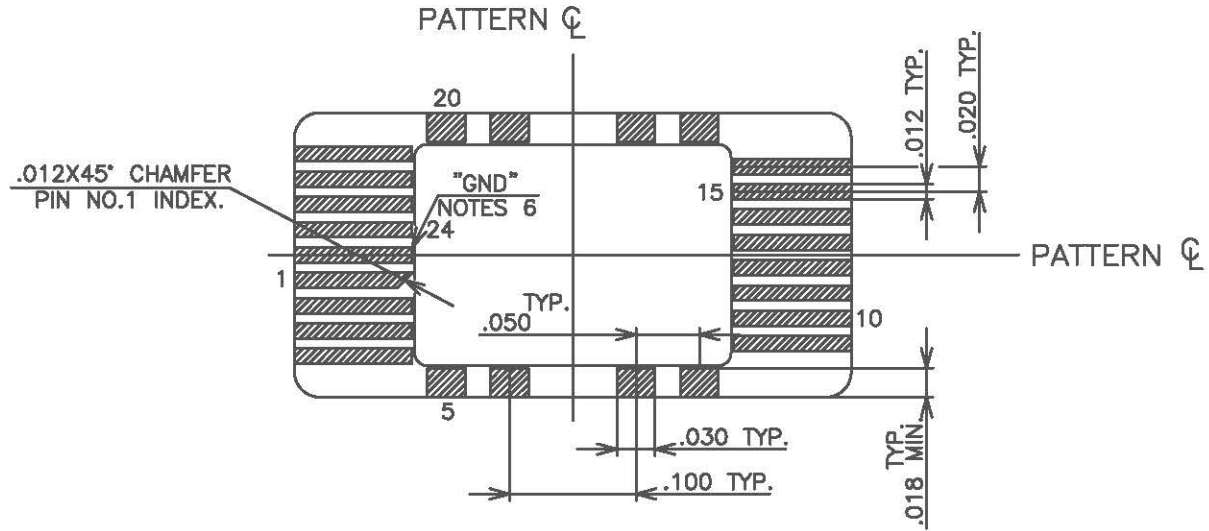
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.3 OHM MAX.
6. DIE ATTACH PAD TO BE ELECTRICALLY CONNECTED TO BONDING PAD "GND".
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.
8. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.

SB024M831-2 S=0 D=0

SB024M831-1 S=0 D=0

MODIFICATION	ADDED : PART No.2 , NOTE 7,8 , DELETED : VENDOR'S OPTION.	APR.17.'09	S.A	H.TA/S.M	K.IM	NAME 24 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN	CHECKED	APPROVED	DATE
	REDRAWN : (CAD DATA)	AUG.06.'91	M.S	S.T/TA	M.K			M.S	S.T/TA	M.K	AUG.06.'91
	ADDED : .018 TYP. MIN.	JUN.06.'83	M.M	K.M							
	ADDED : .005REF., .0015REF., .004REF.	JAN.28.'83	N.I	K.M							
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S82831-D	SHEET			
									1	2	





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.S	S.T/T.A	M.K	AUG.06.'91
						SCALE 10/1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-S82831-D		SHEET	2/2



